



# SOT1172-3

plastic thermal enhanced thin shrink small outline package;  
28 leads; body width 4.4 mm; lead pitch 0.65 mm; exposed  
die pad

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HTSSOP28
<b>Package type industry code</b>	HTSSOP28
<b>Package style descriptive code</b>	HTSSOP (thermal enhanced thin shrink small outline package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	---
<b>JEDEC package outline code</b>	MO-153
<b>JEITA package outline code</b>	---
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-9-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	9.6	-	9.7	9.8	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	[tbd]	-	[tbd]	1.1	mm
A <sub>2</sub>	package height	0.85	-	0.9	0.95	mm
e	nominal pitch	-	-	0.65	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	28	-	

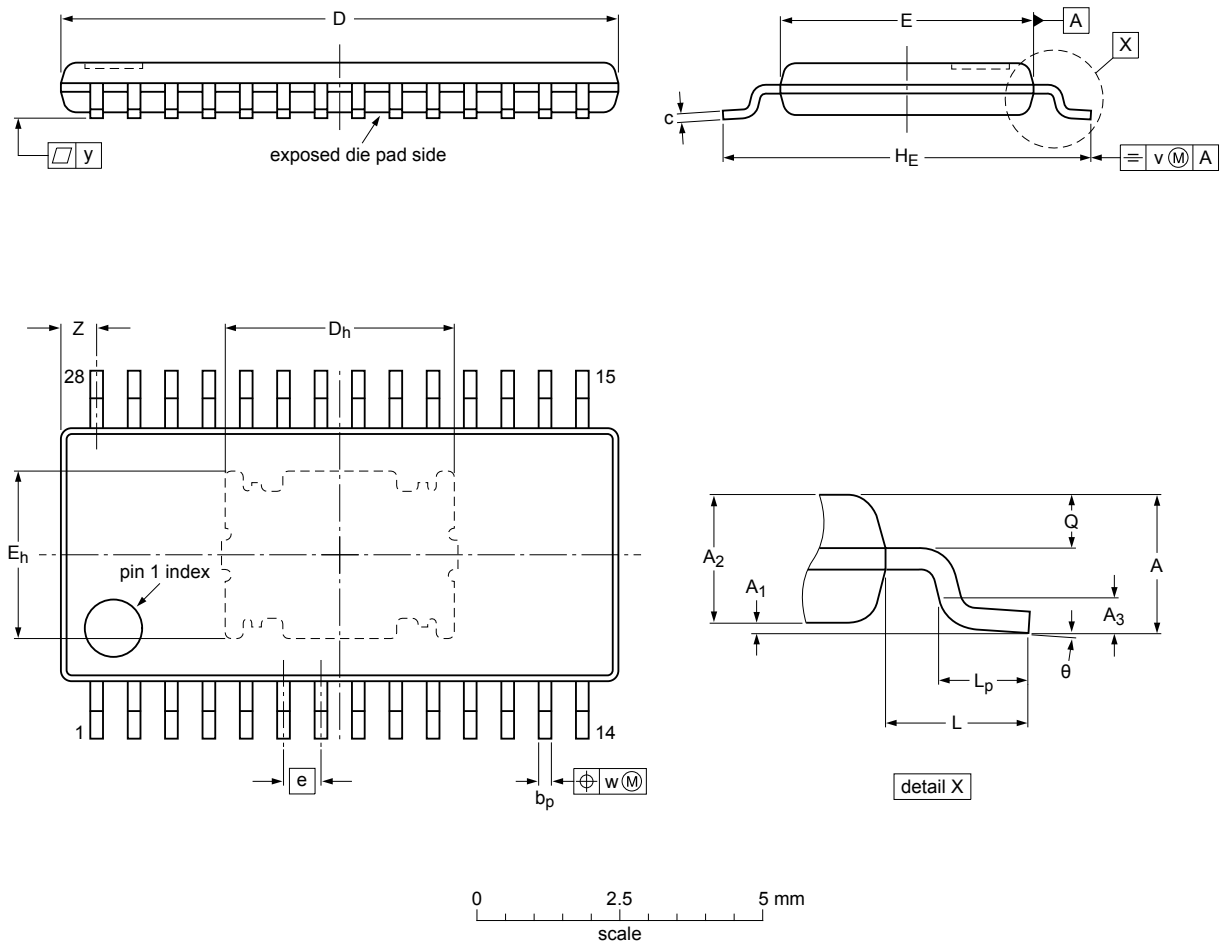


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## 2. Package outline

HTSSOP28: plastic thermal enhanced thin shrink small outline package; 28 leads; body width 4.4 mm; lead pitch 0.65 mm; exposed die pad

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Dimensions (mm are the original dimensions)

Unit	A	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(2)</sup>	E <sub>h</sub>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ	
max	1.1	0.15	0.95		0.30	0.20	9.8	4.1	4.5	3.0		6.6		0.75	0.40					0.80	8°
nom		0.10	0.90	0.25	0.22	0.15	9.7	4.0	4.4	2.9	0.65	6.4	1.0	0.62	0.37	0.2	0.13	0.1	0.63	4°	
min		0.05	0.85		0.19	0.10	9.6	3.9	4.3	2.8		6.2		0.50	0.3					0.50	0°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

sot1172-3\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1172-3	---	MO-153	---		-13-08-20- 13-09-12

Fig. 1. Package outline HTSSOP28 (SOT1172-3)

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### 3. Soldering

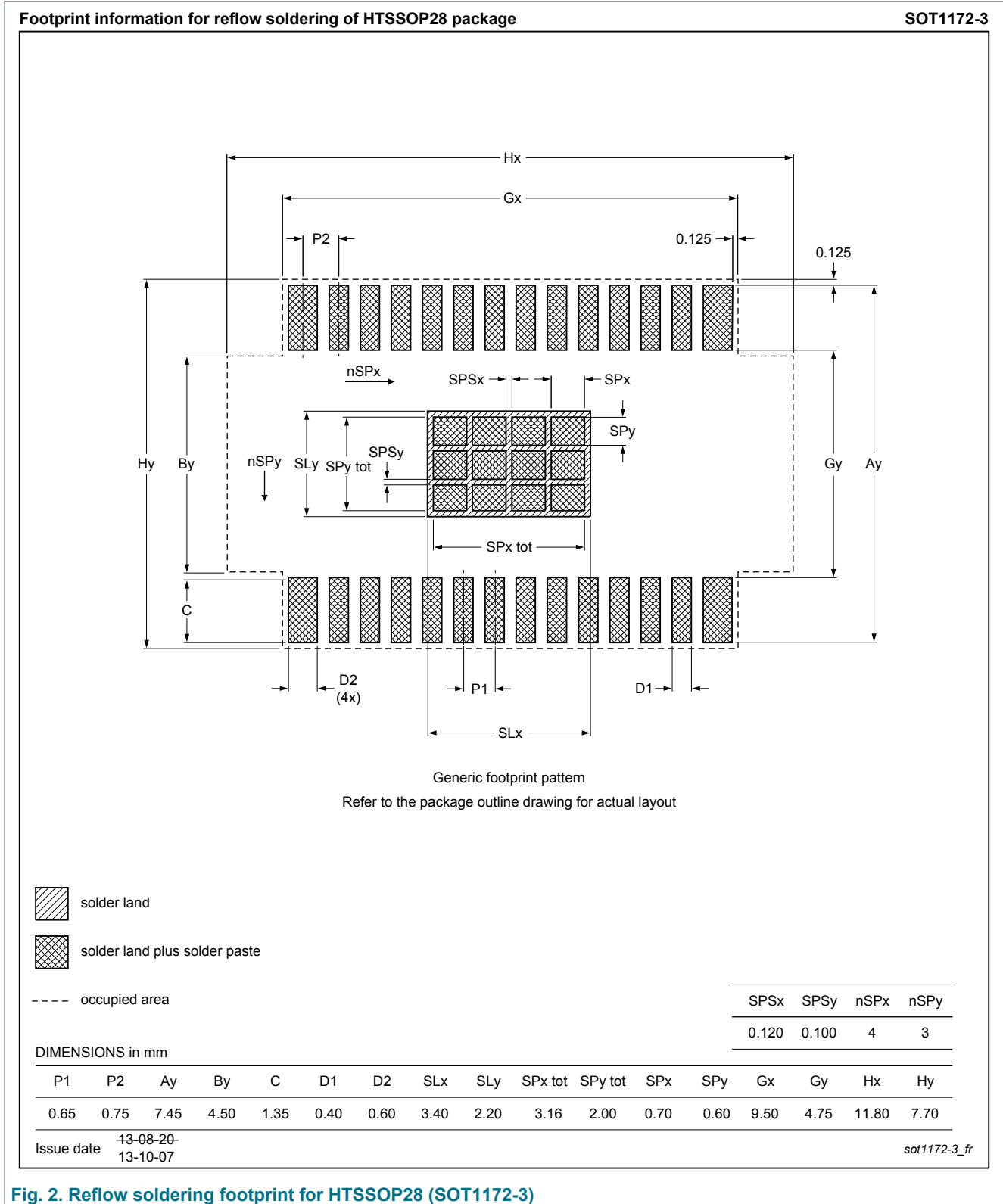


Fig. 2. Reflow soldering footprint for HTSSOP28 (SOT1172-3)

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## 4. Legal information

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